[Released on the Web]

RX Family SPI Mode SD Memory Card Driver

R20TS1007EJ0100 Rev.1.00 Mar, 16, 2024

Firmware Integration Technology

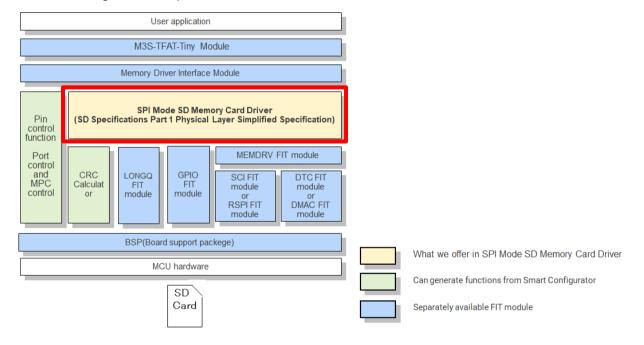
Outline

RX Family SPI Mode SD Memory Card Driver Firmware Integration Technology will be released. This product is available free of charge.

1. Product Features

This application note describes the SPI Mode SD Memory Card driver that uses Firmware Integration Technology (FIT). This module controls SD Memory Cards in SPI mode using the Serial Communication Interface (SCI) or Serial Peripheral Interface (RSPI) included in Renesas Electronics RX Family microcontrollers. In this document, this module is referred to as the SPI mode SD Memory Card driver.

The following shows the position of this module.



This module complies with the Simplified Specification.

When developing host devices that are compliant with the SD Specifications, the user must enter into the SD Card Association License Agreement (SDALA) and SD Card Association Membership Agreement (SDAMA).

For details, refer to the SD Association website.

https://www.sdcard.org/

2. Supported Devices

RX Family MCU

3. Operating Environment

The operating environments are shown below. For details, see "6.1 Operation Confirmation Environment" in the application note.

Integrated Development Environment

- Renesas Electronics e2 studio 2023-10
- IAR Embedded Workbench for Renesas 5.10.1

Compilers

- Renesas Electronics C/C++ Compiler Package for RX Family V.3.05.00
- GCC for Renesas RX 8.03.00.202311
- IAR C/C++ Compiler for Renesas RX 5.10.1

4. Obtaining the Product

Obtain the product from the URL below.

RX Family SPI Mode SD Memory Card Driver Firmware Integration Technology Rev.1.00

 $\underline{\text{https://www.renesas.com/document/scd/rx-family-spi-mode-sd-memory-card-driver-firmware-integration-technology-sample-code}$

5. Reference URL

Firmware Integration Technology (FIT)

https://www.renesas.com/software-tool/fit

FIT module list

https://www.renesas.com/software-tool/fit-modules-list

Revision History

		Description	
Rev.	Date	Page	Summary
1.00	Mar.16.24	-	First edition issued

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Contact information

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